

500V N-Channel Power MOSFET

Features

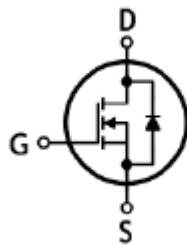
- High Voltage: $BV_{DSS}=500V$ (Min.)
- $I_D : 4.5A$
- Robust high voltage termination
- Avalanche energy specified
- Fast diode recovery time

Application

- Ballast Bridge
- Switch Mode Power Supplier
- Power Factor Correction
- Lighting



I-PAK (Short Lead)



Ordering Information

| Type NO | Marking | Package Code |
|----------|---------|--------------|
| WMI5N50U | 5N50IU | TO-251 |

Absolute maximum ratings ($T_C=25^\circ C$ unless otherwise noted)

| Characteristic | Symbol | | Rating | Unit |
|--------------------------------|-----------|-------------------|----------|------------|
| Drain-source voltage | V_{DSS} | | 500 | V |
| Gate-source voltage | V_{GSS} | | ± 30 | V |
| Drain current (DC) * | I_D | $T_C=25^\circ C$ | 4.5 | A |
| | | $T_C=100^\circ C$ | 2.85 | A |
| Drain current (Pulsed) * | I_{DM} | | 18 | A |
| Single avalanche energy ② | E_{AS} | | 281 | mJ |
| Repetitive avalanche current ① | I_{AR} | | 4.5 | A |
| Repetitive avalanche energy ① | E_{AR} | | 4.8 | Mj |
| Power dissipation | P_D | | 48 | W |
| Junction temperature | T_J | | 150 | $^\circ C$ |
| Storage temperature range | T_{stg} | | -55~150 | $^\circ C$ |

* Limited by maximum junction temperature

| Characteristic | Symbol | Typ. | Max | Unit |
|--------------------|------------------|---------------|-----|--------------|
| Thermal resistance | Junction-case | $R_{th(J-C)}$ | - | 2.6 |
| | Junction-ambient | $R_{th(J-A)}$ | - | 62.5 |
| | | | | $^\circ C/W$ |

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Test Condition | Min. | Typ. | Max. | Unit |
|--------------------------------|--------------------------|--|------|------|-----------|---------------|
| Drain-source breakdown voltage | BV_{DSS} | $I_D=250 \mu\text{A}, V_{GS}=0\text{V}$ | 500 | - | - | V |
| Gate threshold voltage | $V_{GS(\text{th})}$ | $I_D=250 \mu\text{A}, V_{DS}=V_{GS}$ | 3.0 | - | 5.0 | V |
| Drain-source cut-off current | I_{DSS} | $V_{DS}=500\text{V}, V_{GS}=0\text{V}$ | - | - | 1 | μA |
| | | $V_{DS}=400\text{V}, T_c=150^\circ\text{C}$ | | | 10 | μA |
| Gate leakage current | I_{GSS} | $V_{DS}=0\text{V}, V_{GS}=\pm 30\text{V}$ | - | - | ± 100 | nA |
| Drain-source on-resistance | $R_{DS(\text{on})}$ | $V_{GS}=10\text{V}, I_D=2.25\text{A}$ | - | 1.23 | 1.5 | Ω |
| Forward transfer conductance ③ | g_{fs} | $V_{DS}=10\text{V}, I_D=2.25\text{A}$ | - | 4.5 | - | S |
| Input capacitance | C_{iss} | $V_{DS}=25\text{V}, V_{GS}=0\text{V}$ $f=1 \text{ MHz}$ | - | 720 | - | pF |
| Output capacitance | C_{oss} | | - | 61 | - | |
| Reverse transfer capacitance | C_{rss} | | - | 7.5 | - | |
| Turn-on delay time ③④ | $t_{d(\text{on})}$ | $V_{DS}=250\text{V}, I_D=4.5\text{A}$ $R_G=25\Omega$ | - | 35 | - | ns |
| Rise time ③④ | t_r | | - | 26 | - | |
| Turn-off delay time ③④ | $t_{d(\text{off})}$ | | - | 80 | - | |
| Fall time ③④ | t_f | | - | 19 | - | |
| Total gate charge ③④ | Q_g | $V_{DS}=400\text{V}, V_{GS}=10\text{V}$ $I_D=4.5\text{A}$ | - | 12 | 17 | nC |
| Gate-source charge ③④ | Q_{gs} | | - | 5.5 | - | |
| Gate-drain charge ③④ | Q_{gd} | | - | 2.5 | - | |

Source-Drain Diode Ratings and Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Test Condition | Min | Typ | Max | Unit |
|----------------------------|----------|---|-----|------|-----|---------------|
| Source current (DC) | I_S | Integral reverse diode in the MOSFET | - | - | 4.5 | A |
| Source current (Pulsed) | I_{SM} | | - | - | 18 | |
| Forward voltage | V_{SD} | $V_{GS}=0\text{V}, I_{SD}=4.5\text{A}$ | - | - | 1.4 | V |
| Reverse recovery time ③④ | t_{rr} | $I_{SD}=4.5\text{A}, V_{GS}=0\text{V}$ $dI_f/dt=100\text{A}/\mu\text{s}$ | - | 330 | - | ns |
| Reverse recovery charge ③④ | Q_{rr} | | - | 1.15 | - | μC |

Note :

1. Repetitive rating : Pulse width limited by safe operating area
2. $L=25\text{mH}, I_{AS}=4.5\text{A}, V_{DD}=50\text{V}, R_G=25 \Omega, \text{Starting } T_J=25^\circ\text{C}$
3. Pulse Test : Pulse width $\leq 300 \mu\text{s}$, Duty cycle $\leq 2\%$
4. Essentially independent of operating temperature typical characteristics

Electrical Characteristic Curves

Fig. 1 Typical Output Characteristics

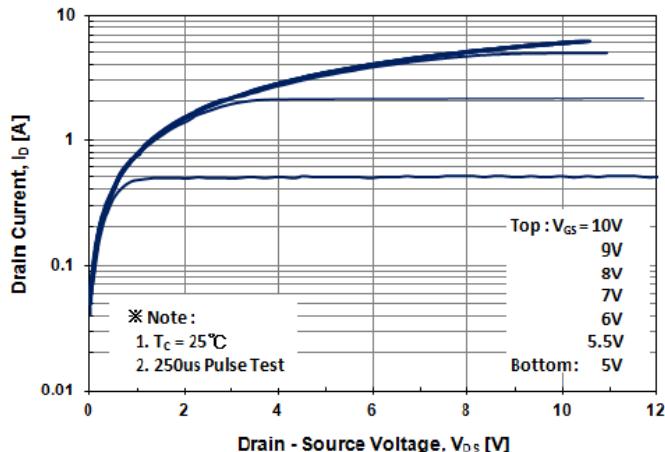


Fig. 2 Typical Output Characteristics

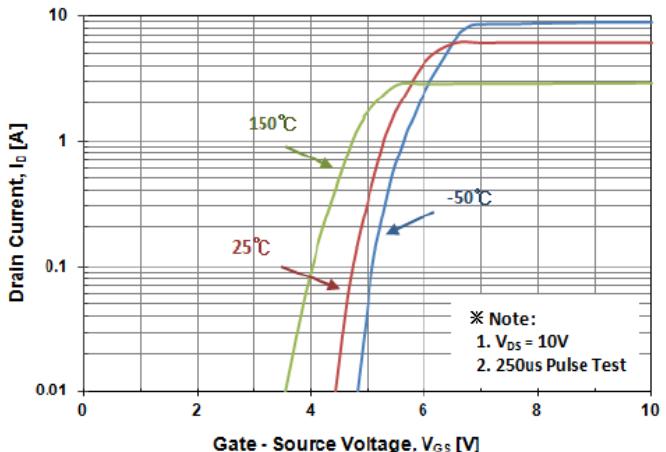


Fig. 3 On-Resistance Variation with Drain Current and Gate Voltage

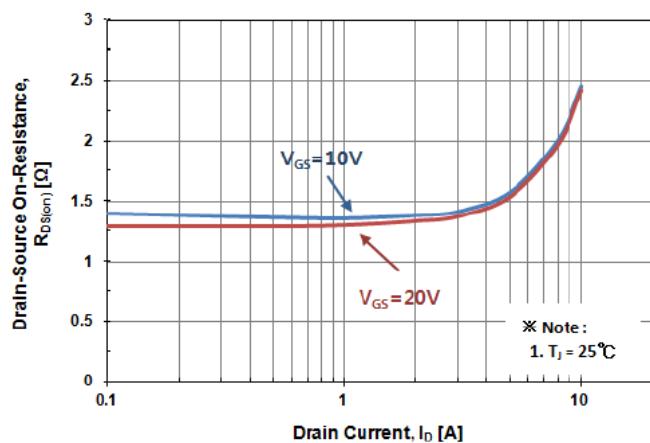


Fig. 4 Body Diode Forward Voltage Variation with Source Current and Temperature

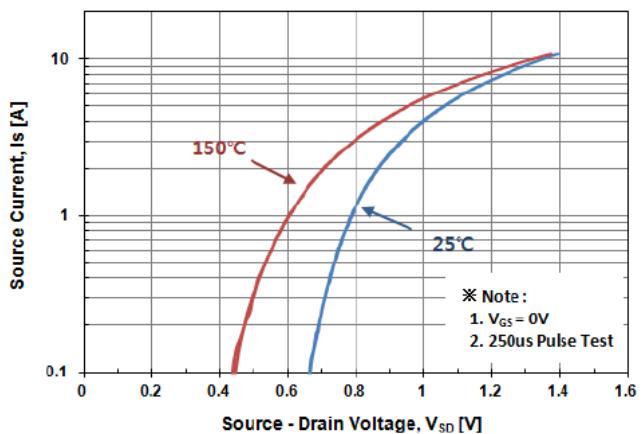


Fig. 5 Typical Capacitance Characteristics

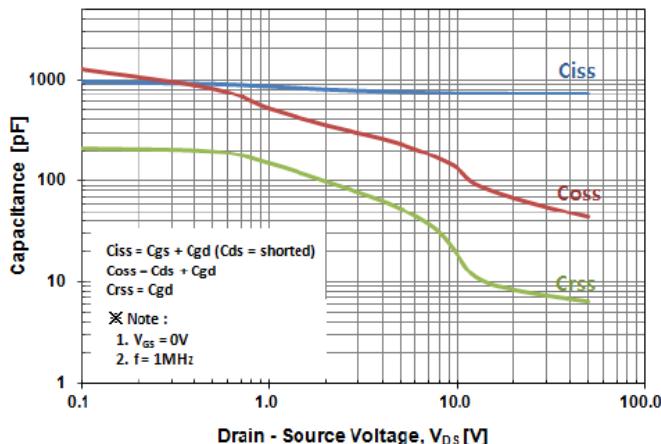
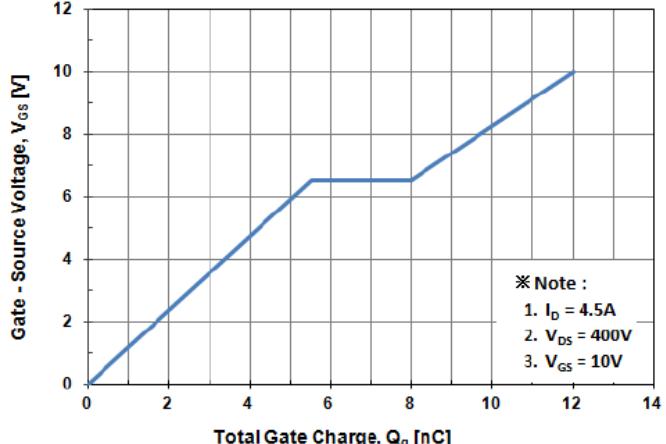


Fig. 6 Typical Total Gate Charge Characteristics



Electrical Characteristic Curves

Fig. 7 Breakdown Voltage Variation vs. Temperature

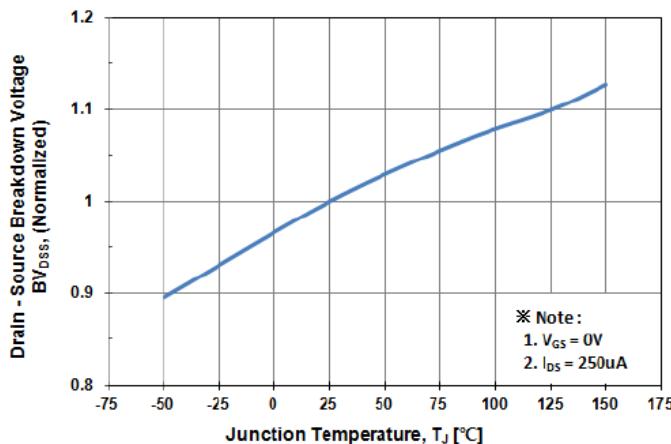


Fig. 8 On-Resistance Variation vs. Temperature

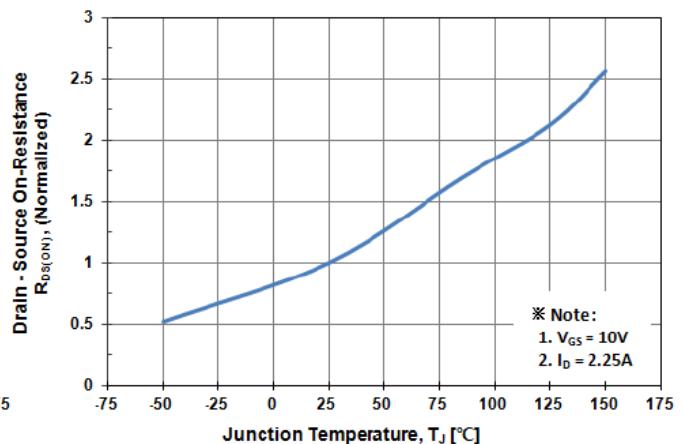


Fig. 9 Maximum Drain Current vs. Case Temperature

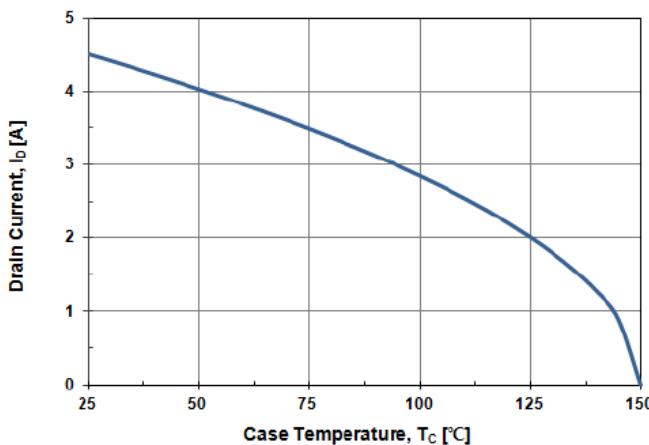


Fig. 10 Maximum Safe Operating Area

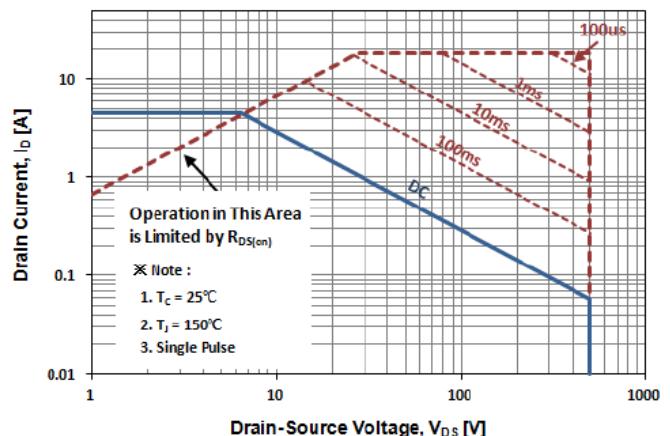
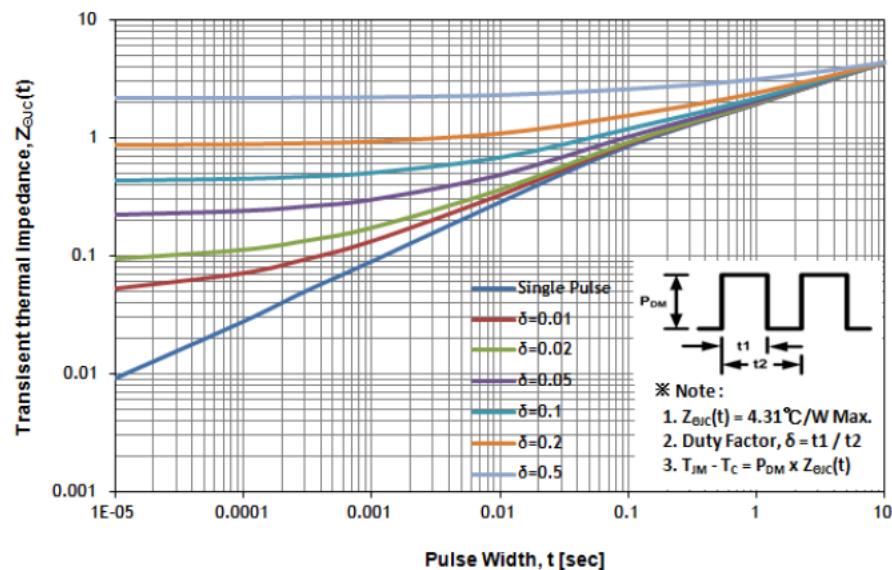
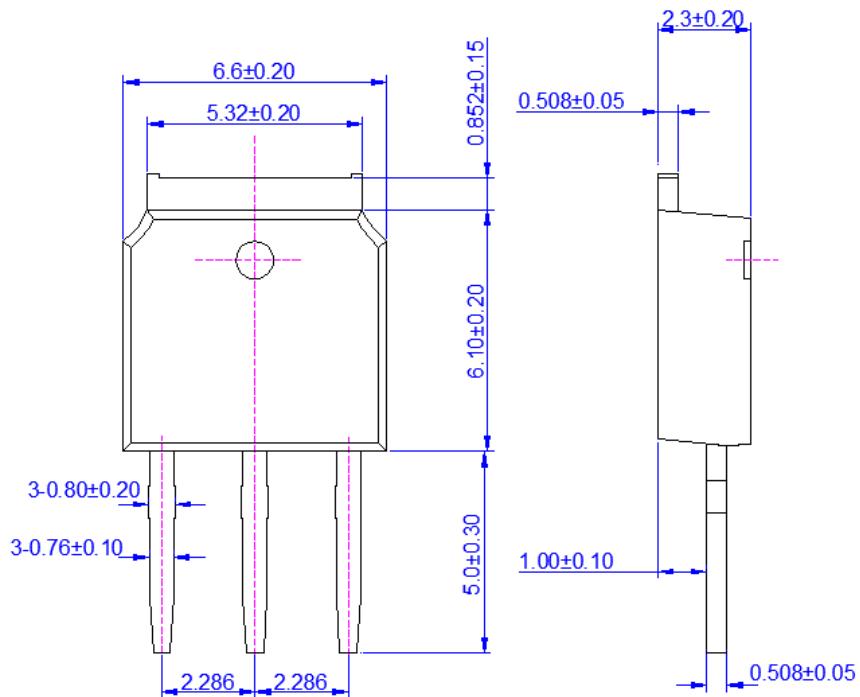
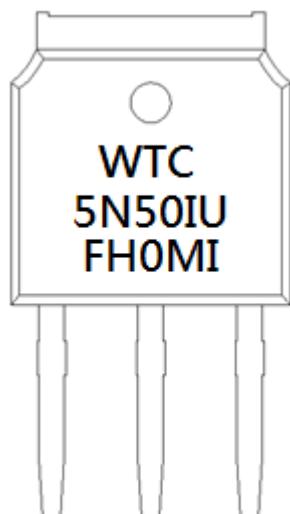


Fig. 11 Transient Thermal Impedance



Outline Dimension : TO-251**Marking Diagram**

| | | | |
|-------------|--------|--------------------|---|
| First Line | WTC | Company Name | |
| Second Line | 5N50IU | Product Code | |
| Third Line | BCOMI | 1st (Year Code) | A-2010 B-2011 C-2012 ... |
| | | 2nd (Month Code) | A-Jan B-Feb C-Mar D-Apr E-May F-Jun G-Jul H-Aug I-Sep J-Oct K-Nov L-Dec |
| | | 3rd (Lot Code) | 0-1 , A-9 |
| | | 4th (Product Code) | M-MOS , T-Transistor |
| | | 5th (Package Code) | D-TO-252 , I-TO-251 |
| | | 6th (Spec Code) | (Reserve) |